High Performance Insulator for Low-Pressure Applications

Features and Benefits

- Thermal impedance: 0.45°C-in²/W (@50 psi)
- · High value material
- · Smooth and highly compliant surface
- Bectrically isolating



The SI-Pad 800 family of thermally conductive insulation materials is designed for applications requiring high thermal performance and electrical isolation. These applications also typically have low mounting pressures for component clamping.

SI-Pad 800 material combines a smooth and highly compliant surface characteristic with high thermal conductivity. These features optimize the thermal resistance properties at low pressure.

Applications requiring low component damping forces include discrete semiconductors (TO-220,TO-247 and TO-218) mounted with spring dips Spring dips assist with quick assembly but apply a limited amount of force to the semiconductor. The smooth surface texture of SI-Pad 800 minimizes interfacial thermal resistance and maximizes thermal performance.

TYPICAL PROPERTIES OF SIL-PAD 800						
PROPERTY	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	Gold		Gold		Visual	
Reinforcement Carrier	Fiberglass		Fiberglass		_	
Thickness (inch) / (mm)	0.005		0.127		ASTM D374	
Hardness (Shore A)	91		91		ASTM D2240	
Hongation (%45° to Warp and Fill)	20		20		ASTM D412	
Tensile Strength (psi) / (MPa)	1700		12		ASTM D412	
Continuous Use Temp (℉) / (℃)	-76 to 356		-60 to 180		_	
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)	1700		1700		ASTM D149	
Type 3 Electrodes	3000		3000		ASTM D149	
Dielectric Constant (1000 Hz)	6.0		6.0		ASTM D150	
Volume Resistivity (Ohm-meter)	10 ¹⁰		10 ¹⁰		ASTM D257	
Hame Rating	V-O		V-O		U.L. 94	
THERMAL						
Thermal Conductivity (W/m-K)	1.6		1.6		ASTM D5470	
THERMAL PERFORMANCE vs PRESSURE						
Press	sure (psi) 10		25	50	100	200
TO-220 Thermal Performance (°C/W)		3.56	3.01	2.45	2.05	1.74
Thermal Impedance (℃-in²/W) (1)		0.92	0.60	0.45	0.36	0.29
1) The ASTM D5/70 feet fixture use used The recorded value includes interfered thermal resistance Them values are provided for						

The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness flatness and pressure applied.

Typical Applications Include:

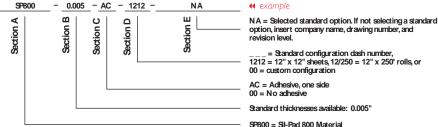
- · Power supplies
- Automotive electronics
- Motor controls
- Power semiconductors

Configurations Available:

- · Sheet form, die-cut parts and roll form
- · With or without pressure sensitive adhesive

Building a Part Number

Standard Options 4 example



Note: To build a part number, visit our website at www.bergquistcompany.com.

SI-Pad®: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others